

HX318C10FW/4

4GB 512M x 64-Bit DDR3-1866
CL10 240-Pin DIMM



SPECIFICATIONS

| | |
|--|-------------------|
| CL(IDD) | 10 cycles |
| Row Cycle Time (tRCmin) | 44.75ns (min.) |
| Refresh to Active/Refresh Command Time (tRFCmin) | 260ns (min.) |
| Row Active Time (tRASmin) | 32.125ns (min.) |
| Maximum Operating Power | TBD W* |
| UL Rating | 94 V - 0 |
| Operating Temperature | 0° C to 85° C |
| Storage Temperature | -55° C to +100° C |

*Power will vary depending on the SDRAM used.

DESCRIPTION

HyperX HX318C10FW/4 is a 512M x 64-bit (4GB) DDR3-1866 CL10 SDRAM (Synchronous DRAM) 1Rx8 memory module, based on eight 512M x 8-bit DDR3 FBGA components. This module has been tested to run at DDR3-1866 at a low latency timing of 10-11-10 at 1.5V. Additional timing parameters are shown in the PnP Timing Parameters section below. The JEDEC standard electrical and mechanical specifications are as follows:

Note: The PnP feature offers a range of speed and timing options to support the widest variety of processors and chipsets. Your maximum speed will be determined by your BIOS.

PnP JEDEC TIMING PARAMETERS:

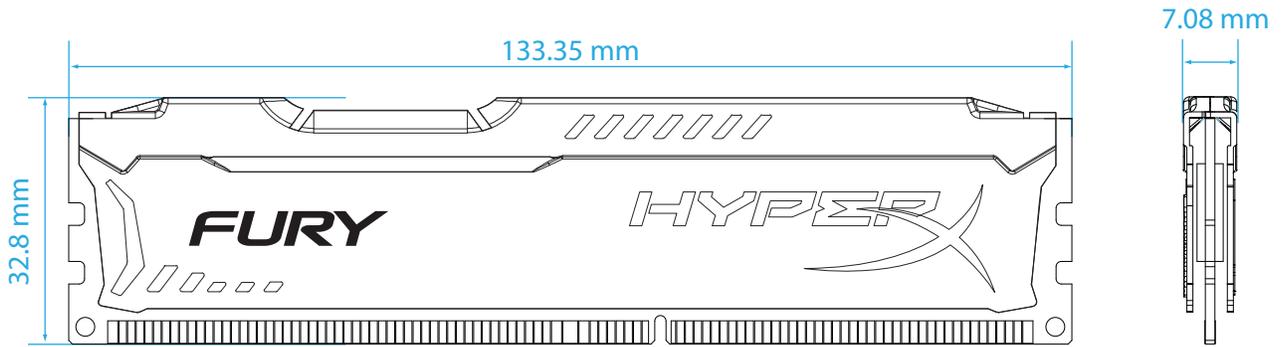
- DDR3-1866 CL10-11-10 @1.5V
- DDR3-1600 CL9-10-9 @1.5V
- DDR3-1333 CL8-9-8 @1.5V

FEATURES

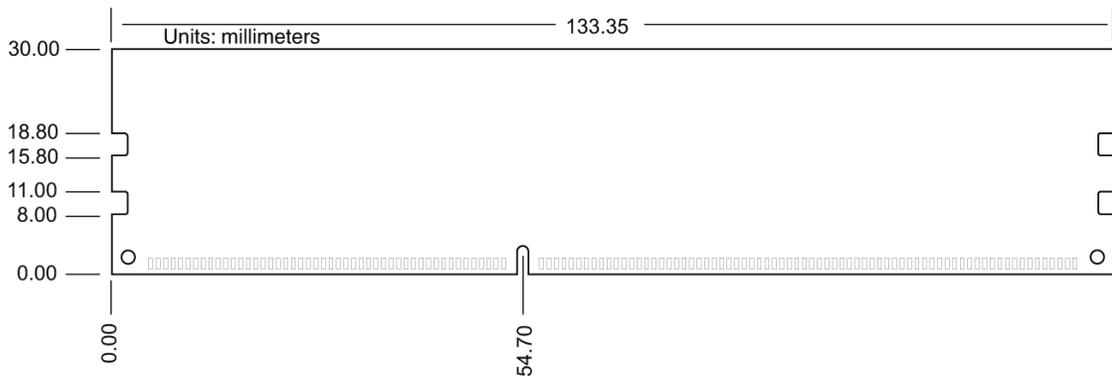
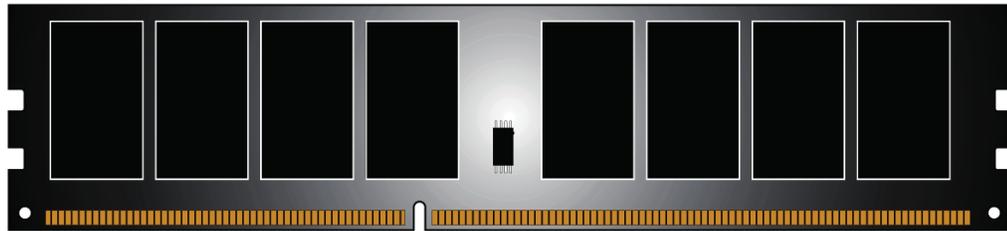
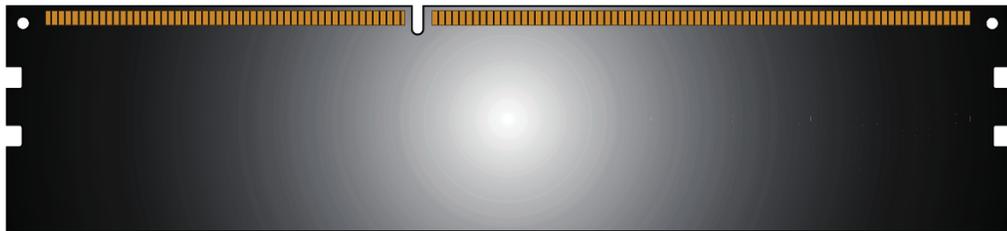
- JEDEC standard 1.5V (1.425V ~1.575V) Power Supply
- VDDQ = 1.5V (1.425V ~ 1.575V)
- 933MHz fCK for 1866Mb/sec/pin
- 8 independent internal bank
- Programmable CAS Latency: 13, 11, 10, 9, 8, 7, 6
- Programmable Additive Latency: 0, CL - 2, or CL - 1 clock
- 8-bit pre-fetch
- Burst Length: 8 (Interleave without any limit, sequential with starting address "000" only), 4 with tCCD = 4 which does not allow seamless read or write [either on the fly using A12 or MRS]
- Bi-directional Differential Data Strobe
- Internal(self) calibration : Internal self calibration through ZQ pin (RZQ : 240 ohm ± 1%)
- On Die Termination using ODT pin
- Average Refresh Period 7.8us at lower than TCASE 85°C, 3.9us at 85°C < TCASE ≤ 95°C
- Asynchronous Reset
- Height 1.291" (32.80mm) w/heatsink, single sided component

Continued >>

MODULE WITH HEAT SPREADER



MODULE DIMENSIONS



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